

R276

Dispensable No-Clean Solderpaste for Lead-free Alloys

Product Description

Kester R276 is a lead-free, no-clean solder paste specifically designed for optimal characteristics in all types of dispensing applications. R276 is packaged void-free to insure consistent dispensing in high speed automated processes. The flow characteristics of R276 provide for excellent dispensing characteristics with a wide range of needle diameters.

- Excellent dispensing characteristics using 22 gage needles and Type 3 powder
- Manufactured and packaged void-free to insure the most consistent dispensability available
- Capable of several thousands of dots per hour in high speed automated dispense equipment
- High activity on all substrates, including OSPs
- Stable tack over 8+ hours
- Available with leaded alloys
- Compatible with Kester Easy Profile® 256 stenciling solderpaste
- Classified as ROL0 per J-STD-004
- Compliant to Bellcore GR-78

Standard Application

86% Metal -- Dispensing

RoHS Compliance

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances.

Physical Properties

(Data given for Sn96.5Ag3.0Cu0.5 86% metal, -325+500 mesh)

Viscosity (typical): 650 poise

Malcom Viscometer @ 10rpm and 25°C

Initial Tackiness (typical): 30 grams

Tested to J-STD-005, IPC-TM-650, Method 2.4.44

Slump Test: Pass

Tested to J-STD-005, IPC-TM-650, Method 2.4.35

Solder Ball Test: Preferred

Tested to J-STD-005, IPC-TM-650, Method 2.4.43

Wetting Test: Pass

Tested to J-STD-005, IPC-TM-650, Method 2.4.45

Reliability Properties

Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.3

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

SIR, IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	R276
Day 1	$1.0 \times 10^{10} \Omega$	$9.8 \times 10^8 \Omega$
Day 4	$1.3 \times 10^{10} \Omega$	$1.6 \times 10^9 \Omega$
Day 7	$1.3 \times 10^{10} \Omega$	$1.1 \times 10^9 \Omega$

Application Notes

Availability:

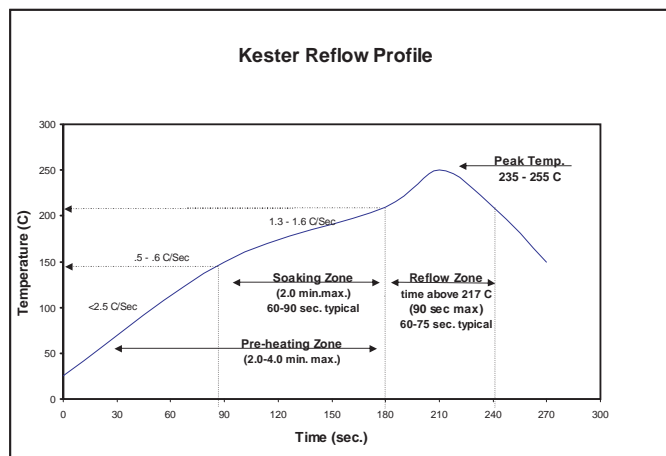
R276 is available in the Sn96.5Ag3.0Cu0.5 and Sn96.5Ag3.5 alloys. Type 3 powder mesh is recommended, but Type 4 is available for fine needle applications. R276 is also compatible with other SnAgCu alloys in a similar melting range to the listed alloys. R276 is available only in 10cc and 30cc syringes. For specific packaging information, see Kester's Solder Paste Chart.

Dispensing Parameters:

Needle diameter	Type 3 powder may be used with needle sizes down to 22 gauge. Type 4 powder may be used for finer needle applications.
Dispense Speed	Capable of at least 4 dots per second
Temperature/Humidity	Optimal ranges are 21-25°C (70-77°F) and 35-65% R.H.

Recommended Reflow Profile:

The recommended reflow profile for R276 made with SAC alloys is shown here. This profile is simply a guideline. Since R276 is a highly active solderpaste, it can solder effectively over a wide range of profiles. Your optimal profile may be different from the one shown based on you oven, board and mix of defects. Please contact Kester if you need additional profiling advice.



Cleaning:

R276 is a no-clean formula. The residues do not need to be removed for typical applications. Although R276 is designed for no-clean applications, its residues can be easily removed using automated cleaning equipment (in-line or batch) with a variety of readily available cleaning agents. Call Kester Technical Support for details.

Storage, Handling, and Shelf Life:

Refrigeration is the recommended optimum storage condition for solderpaste to maintain consistent viscosity, reflow characteristics and overall performance. R276 should be stabilized at room temperature prior to dispensing. R276 should be kept at standard refrigeration conditions, 0-10°C (32-50°F). Please contact Kester if you require additional advice with regard storage and handling of this material. Shelf life is 6 months from date of manufacture when handled properly when held at 0-10°C (32-50°F).

Health & Safety:

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

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